



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<b>TO:</b>	Please return this copy as a certification of your approval
<b>Part No.:</b>	<b>Checked &amp; Approved by:</b>
<b>Customer's Part No.:</b>	<b>Date:</b>

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Part No.	:	SDL6105
Pages	:	4
Date	:	2017/1/6
Revision	:	1.0

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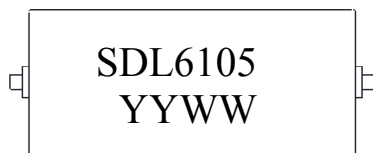
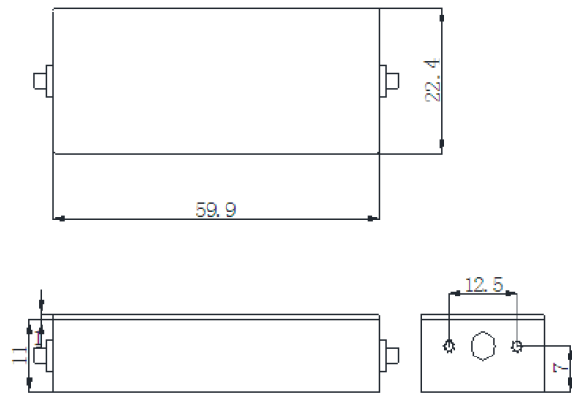
**Application**

- High-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 200 MHz

**Features**

- **RoHS** compatible
- Package size 59.9x22.4x11.0mm<sup>3</sup>
- Package Code MXSS6023-P2BA
- **Electrostatic Sensitive Device(ESD)**

**Package Dimensions (Unit: mm)**



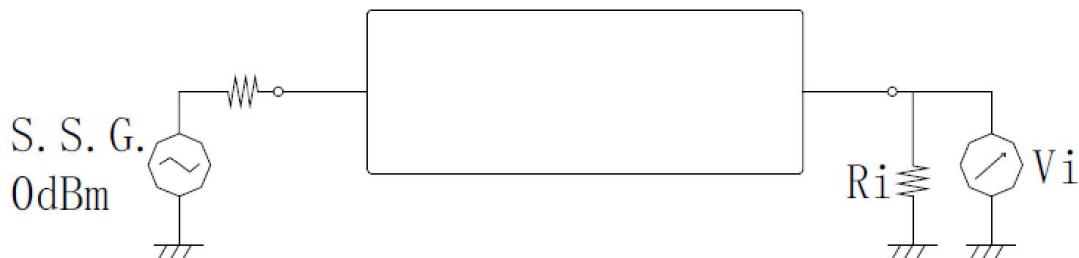
Connected By SMA-K

**Marking Description**

<b>S</b>	Trademark
<b>DL</b>	Delay Line
<b>6105</b>	Part Number
<b>YYWW</b>	Year Code & Week Code

\*Fig: If the products produced in 06<sup>th</sup> week of 2012,  
The year code & week code is 1206.

**Test Circuit**



## Performance

### Maximum Rating

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

### Electronic Characteristics

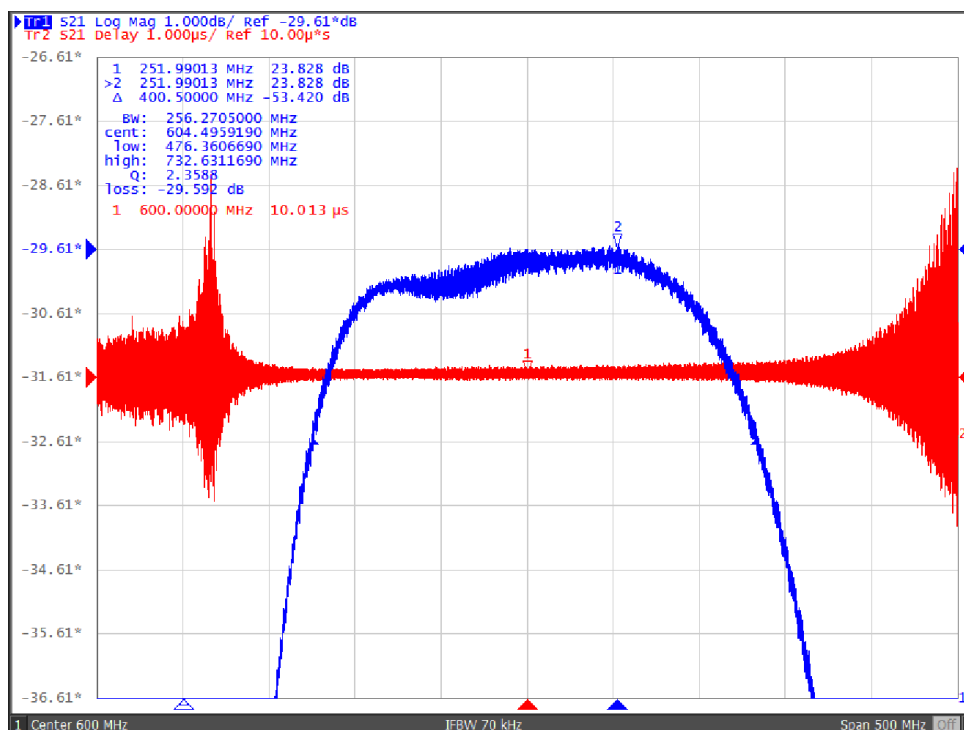
Test Temperature: 25°C ± 2°C

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

Item		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		600.0		MHz
Insertion Loss(min)	IL		29.6	40.0	dB
3dB Bandwidth	BW <sub>3dB</sub>	200.0	256.2		MHz
Absolute Delay	AD	9.917	10.013	10.017	us
	@600.0MHz				

### Frequency Characteristics



**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.